

Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

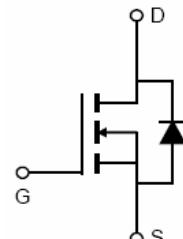
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- $V_{DS} = 85V, I_D = 290A$
- $R_{DS(ON)} = 1.8m\Omega$, typical@ $V_{GS} = 10V$
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating



TO-247



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST08N018-T7	VST08N018	TO-247	-	-	-

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	85	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	290	A
Drain Current-Continuous($T_c=100^\circ C$)	$I_D (100^\circ C)$	220	A
Pulsed Drain Current	I_{DM}	1160	A
Maximum Power Dissipation	P_D	300	W
Derating factor		2	W/°C
Single pulse avalanche energy ^(Note 5)	E_{AS}	2880	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.5	°C/W
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Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	85		-	V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=85\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	2.0	3.0	4.0	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=145\text{A}$	-	1.8	2.3	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=145\text{A}$		200	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=40\text{V}, \text{V}_{\text{GS}}=0\text{V},$ $F=1.0\text{MHz}$	-	14500	-	PF
Output Capacitance	C_{oss}		-	2050	-	PF
Reverse Transfer Capacitance	C_{rss}		-	105	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{\text{d(on)}}$	$\text{V}_{\text{DD}}=40\text{V}, \text{I}_D=145\text{A}$ $\text{V}_{\text{GS}}=10\text{V}, \text{R}_G=1.6\Omega$	-	41	-	nS
Turn-on Rise Time	t_r		-	37	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	103	-	nS
Turn-Off Fall Time	t_f		-	38	-	nS
Total Gate Charge	Q_g	$\text{V}_{\text{DS}}=40\text{V}, \text{I}_D=145\text{A},$ $\text{V}_{\text{GS}}=10\text{V}$	-	240	-	nC
Gate-Source Charge	Q_{gs}		-	61	-	nC
Gate-Drain Charge	Q_{gd}		-	72	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=145\text{A}$	-		1.2	V
Diode Forward Current	I_s		-	-	290	A
Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}, I_F = 145\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$ (Note 3)	-	106	-	nS
Reverse Recovery Charge	Q_{rr}		-	309	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition : $T_J=25^\circ\text{C}, V_{\text{DD}}=40\text{V}, V_G=10\text{V}, L=0.5\text{mH}, R_g=25\Omega$

Typical Electrical and Thermal Characteristics

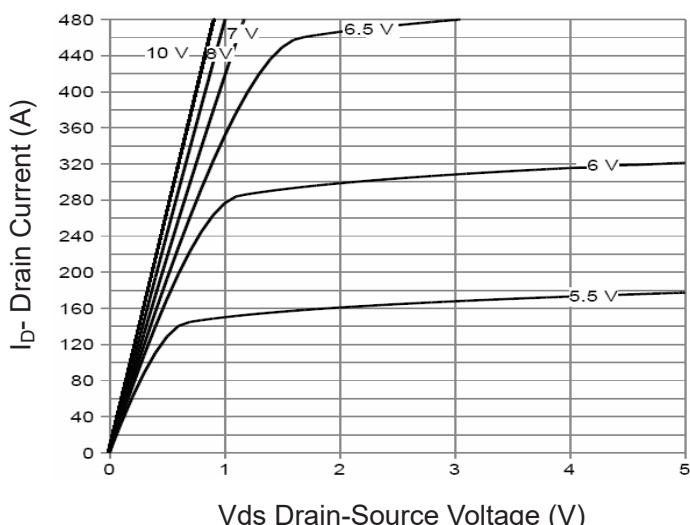


Figure 1 Output Characteristics

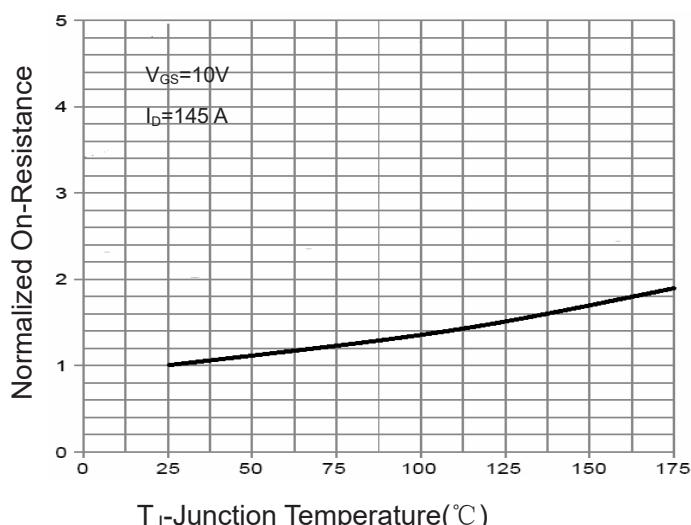


Figure 4 Rdson-Junction Temperature

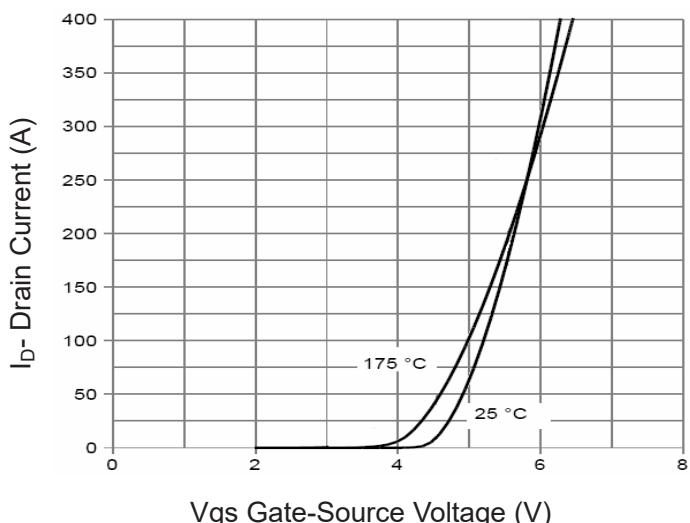


Figure 2 Transfer Characteristics

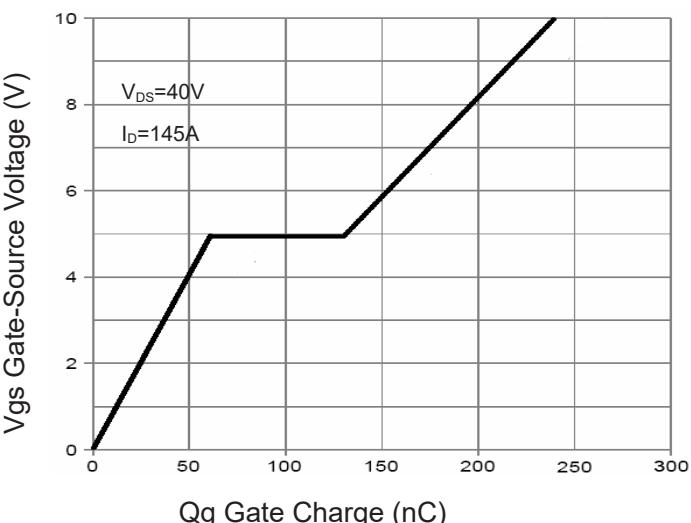


Figure 5 Gate Charge

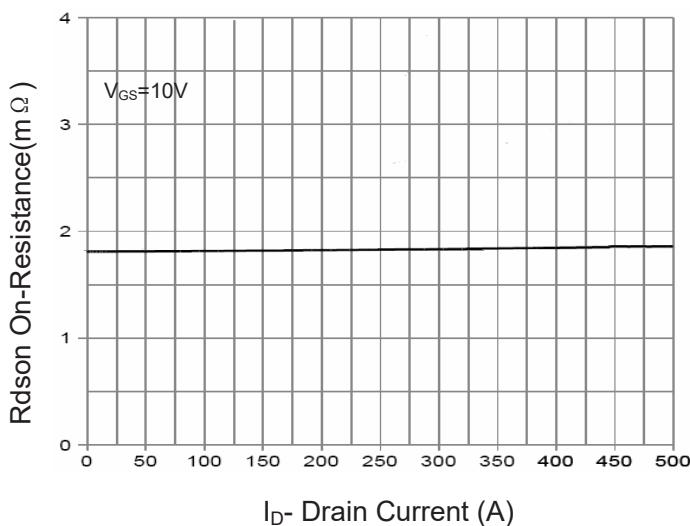


Figure 3 Rdson- Drain Current

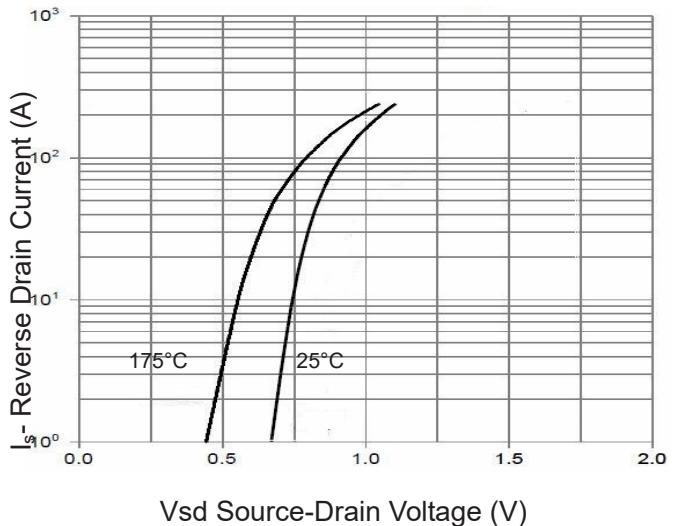


Figure 6 Source- Drain Diode Forward

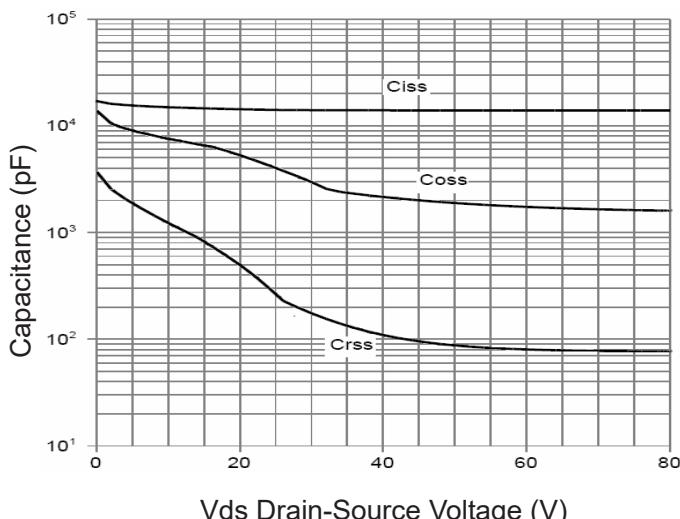


Figure 7 Capacitance vs Vds

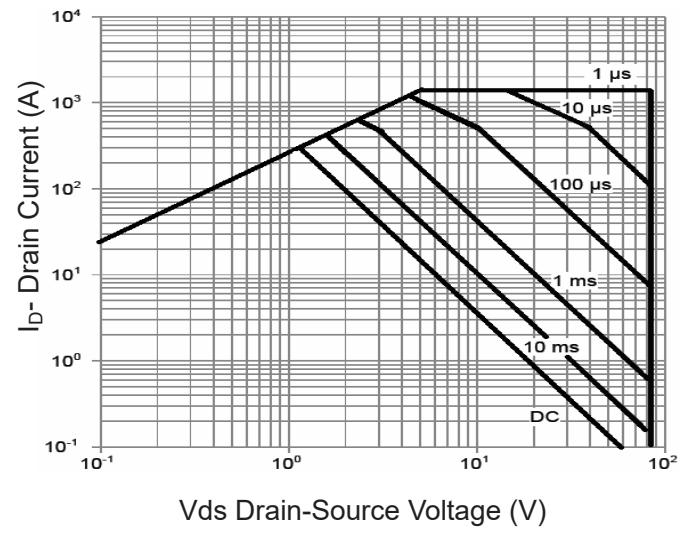


Figure 8 Safe Operation Area

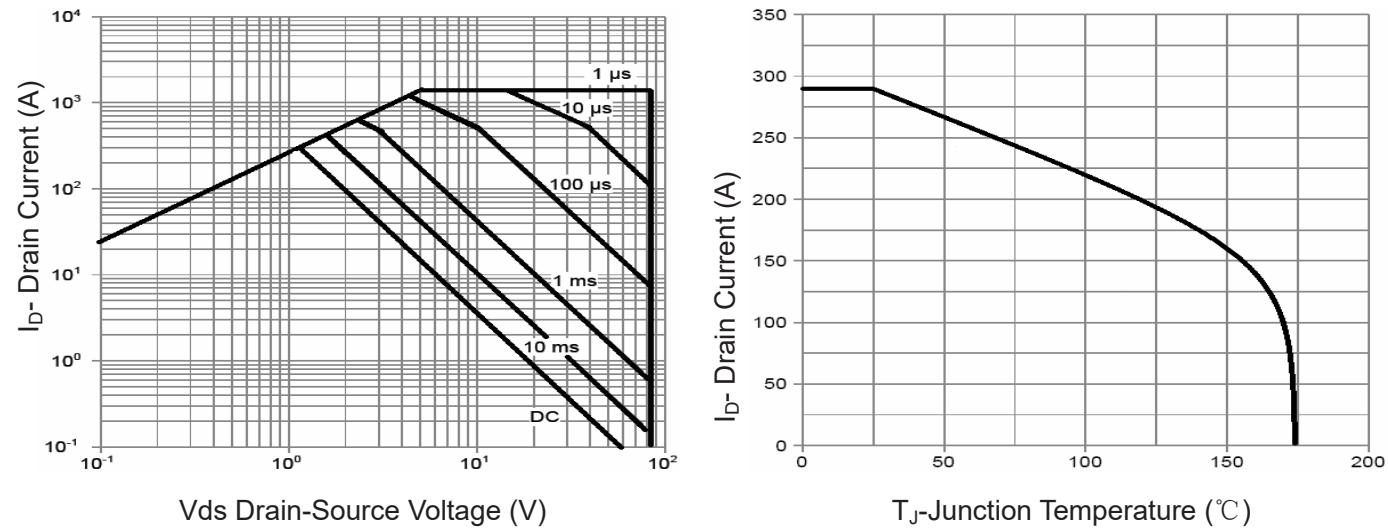


Figure 9 Power De-rating

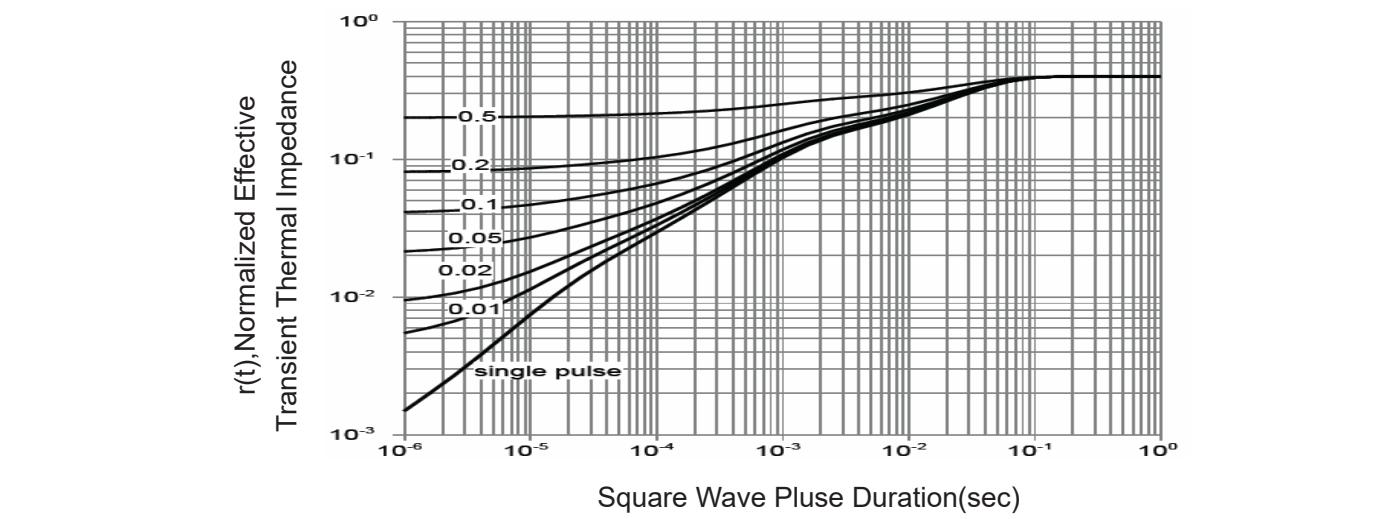


Figure 10 Current De-rating

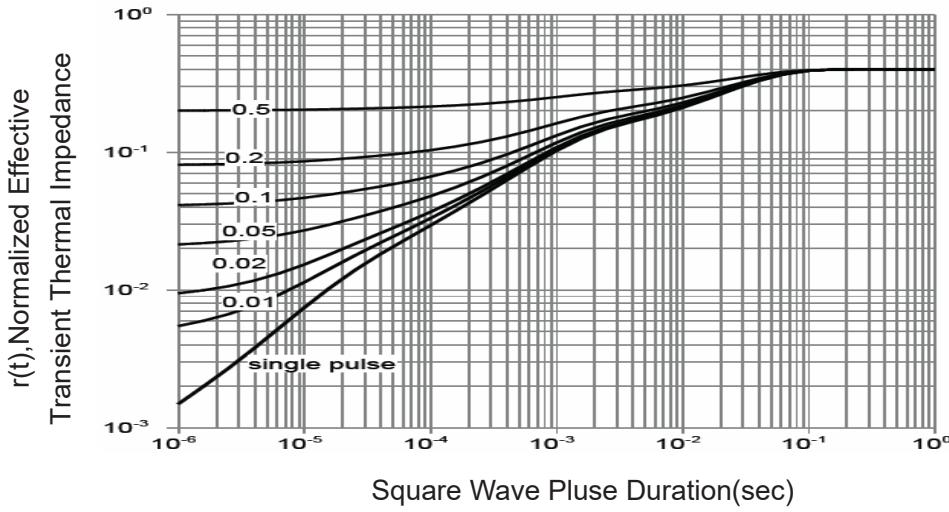


Figure 11 Normalized Maximum Transient Thermal Impedance